

/ Descriptions

TO-277

TO-277 Plastic package Schottky diode .

/ Features

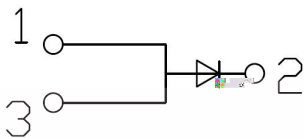
$$V_F(\text{typ})=0.21\text{V}$$

High Forward Surge Capability, Ultra Low Forward Voltage Drop $V_F(\text{typ})=0.21\text{V}$, Excellent High Temperature Stability. HF Product.

/ Applications

For use in low voltage,high frequency inverters, free wheeling, and polarity protection applications.

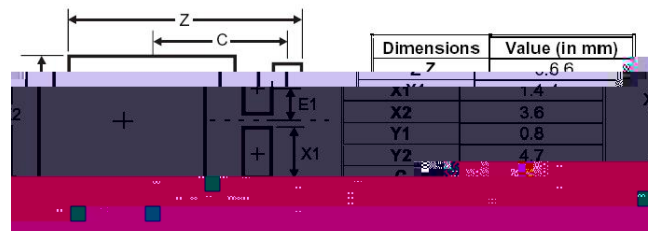
/ Equivalent Circuit



/ Pinning



PIN1 Anode PIN 2 Cathode PIN 3 Anode



Suggested Pad layout

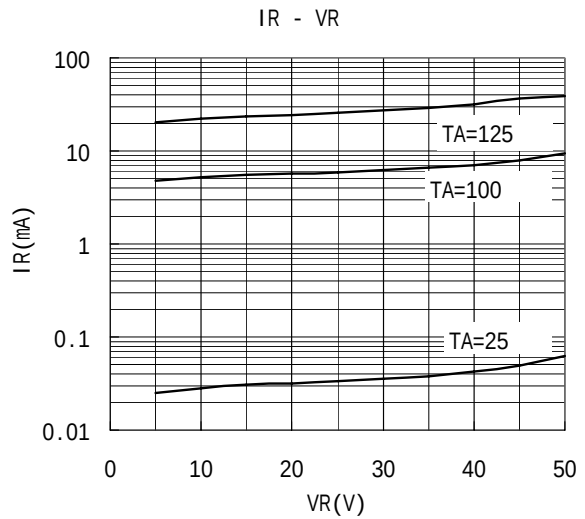
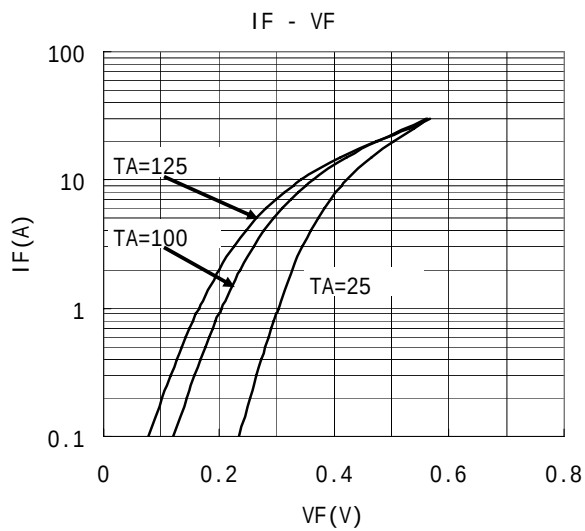
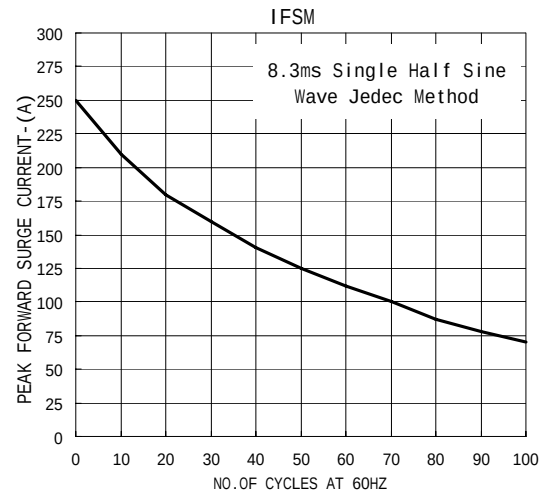
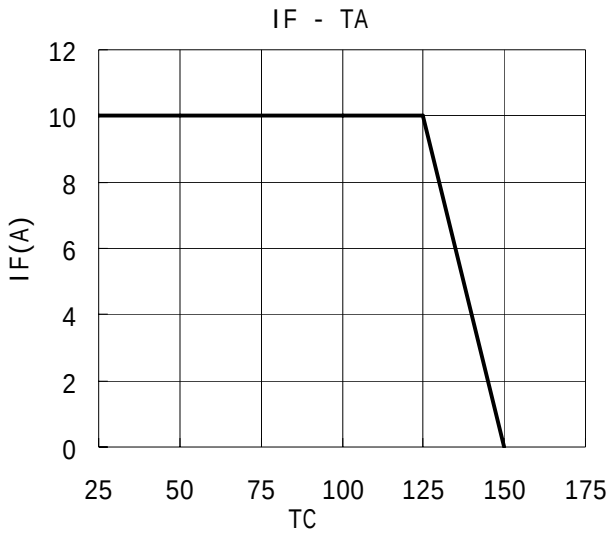
/ h_{FE} Classifications & Marking

See Marking Instructions.

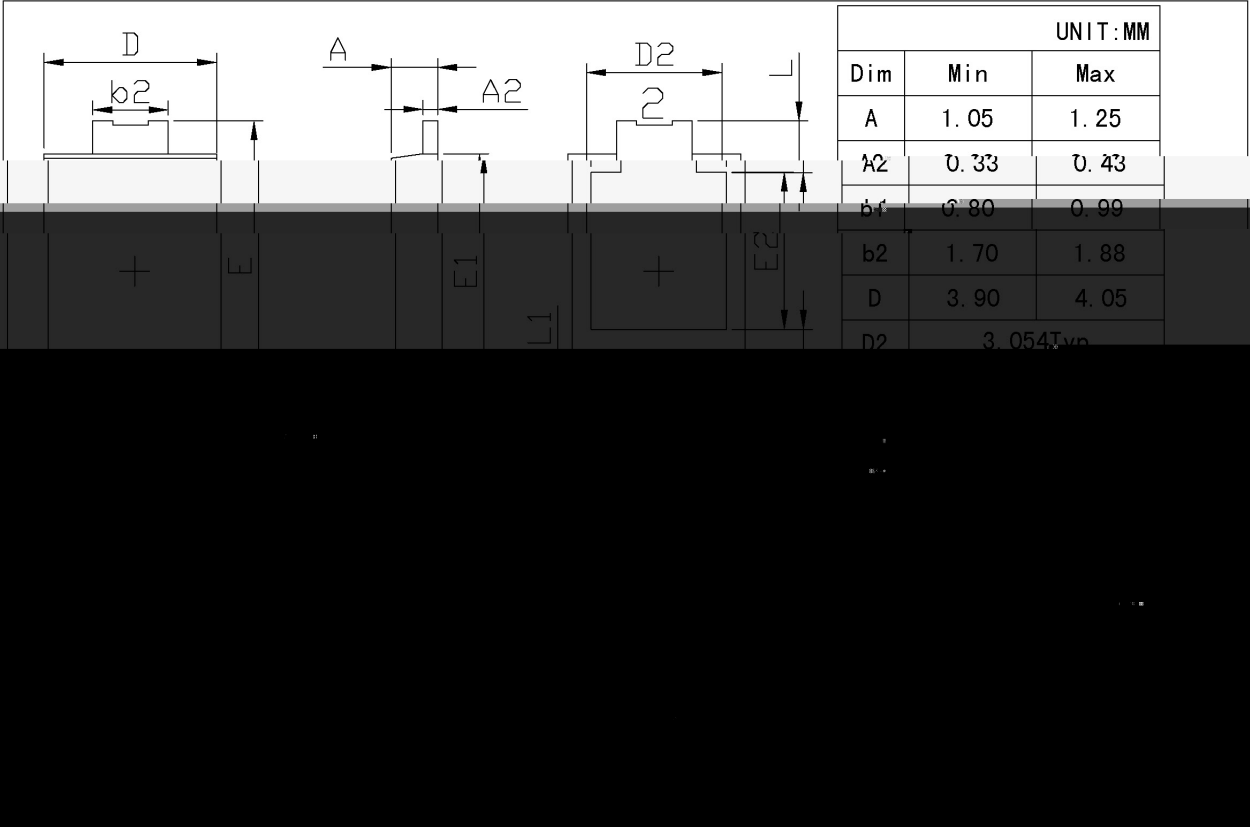
Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage Peak Reverse Voltage	V_{RRM} V_{RWM} V_{RM}	45	V
RMS Reverse voltage	$V_{R(RMS)}$	35	V
Average Rectified Output Current	I_O	10	A
Non-Repetitive Peak Forward Surge Current	I_{FSM}	250	A
Junction Temperature Range	$T_{j\ MAX}$	150	
Storage Temperature Range	T_{stg}	-55 150	
Typical Thermal Resistance	R_{JA} Note 1	73	/W

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_R	I_R				

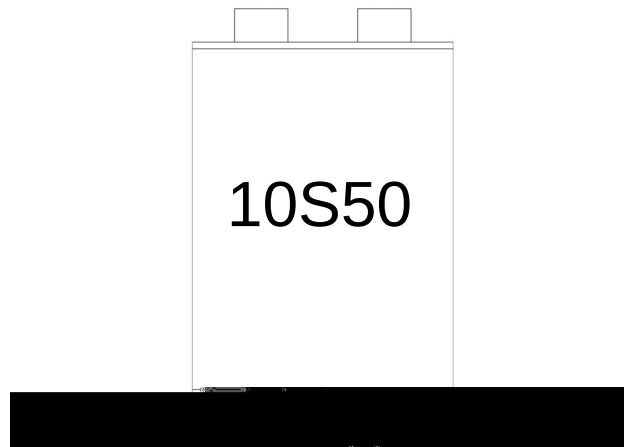
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



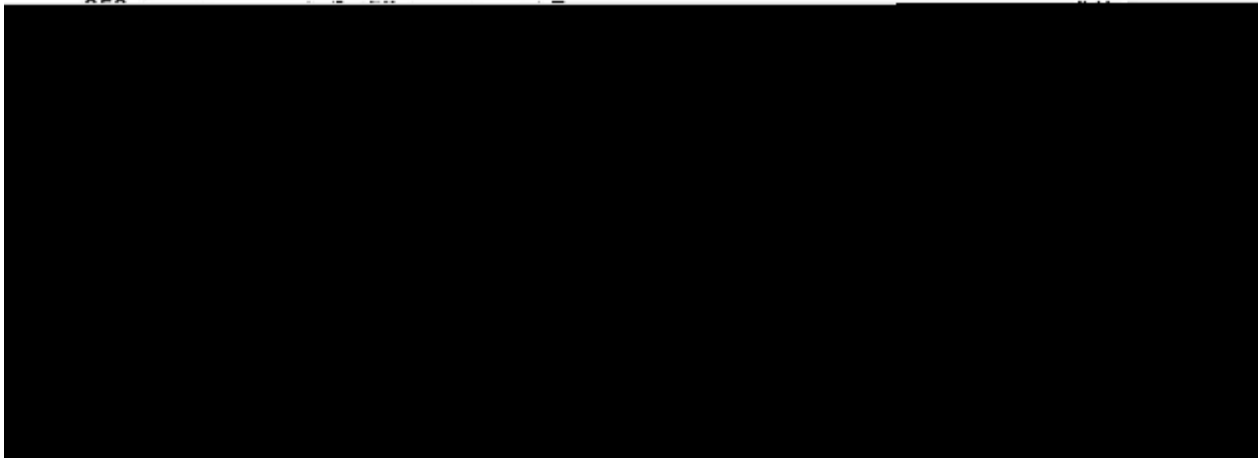
Note:

Product Type.

****:

Lot No. Code, code change with Lot No.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|----------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245 | 5 | 5 | 0.5sec; | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱

/ Notices